

Q1. Draw neat & clean circuit level implementation for the function using static CMOS topology.

$$\text{Out} = [(A \cdot B) + (C \cdot D) + (A \cdot D \cdot (E + F))]$$

Assuming that for this technology $R_p = (1/3) * R_N$

- Now, size your gate such that the worst-case pull up resistance is equal to the worst-case pull-down resistance, assuming that the minimum transistor width is 1.
- Now determine the worst case propagation delay assuming load capacitance of 50fF and equivalent resistance for NMOS is $R_n = 180k\Omega$ & $R_p = 60k\Omega$ for unit transistors ($W=1$).
- Also, calculate the logical effort of this gate from the A, C and E inputs?
- Now find out the euler path if exists and draw a labelled neat and clean layout(optimized for area) of the entire circuit [10]

Q2. A 2-Input NAND gate is designed as a universal gate to implement complex boolean functions using minimum size transistors, $V_{tn}=|V_{tp}|=0.6V$ and $V_{DD} = 3.3V$. Suppose the $K_n = 0.2mA/V^2$ for the pullup equivalent of the NAND gate and $K_p = 0.1mA/V^2$ for pull down equivalent of NAND gate.

- Now, determine the switching threshold voltage V_M of NAND gate.
- Calculate the equivalent resistance for each transistor of this equivalent inverter (using our general expression for MOSFET resistance in saturation or at edge of saturation).
- Now, use RC delay model to calculate the rise and fall times of this circuit if the parasitic capacitance at the output is 12 fF.
- Also calculate the propagation delay for this circuit if a load capacitances of 22fF is added at the output (use RC delay model)?
- Now, use the inverter equivalent of NAND gate and design a ring oscillator (11-stages). Determine the frequency of operation of ring oscillator. Also determine the dynamic power consumption of a single cmos inverter stage for given (load+parasitic) capacitance driven by it. [10]

Q3. Draw a labelled NOR based 4 x 6-bit ROM circuit to store the following set of information at each of the rows. [8]

- Row1 (Word 1): 010101
- Row2 (Word 2): 011001
- Row3 (Word 3): 100101
- Row4 (Word 4): 101010

Q4. A CMOS memory cell uses one nMOS access transistor and a storage capacitor to save data.

- What type of memory is this?
- If the nMOS access transistor has $V_{tn}=0.6V$ and $\mu_n = 500cm^2/V$, what is the maximum voltage that can be stored with $V_{DD}=3V$?
- Assume 1×10^{-13} coulombs of charge are stored on this cell at a max storage voltage = 2.5V. If the minimum cell readout voltage is 0.5V, what is the maximum allowable leakage current for a hold time of 1 μ sec ?
- If the minimum voltage after charge leakage on the cells is 1V, what is the final bit line voltage if $C_s = 30fF$ (capacitor) and $C_{bit} = 0.27pF$? [8]

Q5. Assume that your entire M.E batch has worked on a new process technology and developed standard cells (for all gates and blocks) having an average switching capacitance of **120pF/mm²** and operating at $V_{DD} = 0.9V$. Being an ASIC design engineer you are going to synthesize a sub-system using these standard cell with an average activity factor of **0.1**. Now, estimate the dynamic

